

ABSTRACT

In one exemplary embodiment, a substrate processing system is provided. A controller is configured to perform (a), (b), (c), and (d). The (a) includes moving a plurality of lifter pins upward in order to cause a
5 ring member to self-guide so that tips of the plurality of lifter pins are respectively positioned within a plurality of recesses by lifting the ring member disposed on a ring support surface. The (b) includes moving the plurality of lifter pins downward in order to lower the lifted ring member onto the ring support surface. The (c) includes detecting the
10 position of the ring member by a position detector. The (d) includes transferring a substrate to a substrate support surface based on the position of the ring member.